

REMARKS

Applicants respectfully request reconsideration of this application as amended. Claims 1, 5, 8, 11, 13-14 and 17-18 have been amended. Claims 12, 16 and 19-29 have been cancelled without prejudice. Therefore, claims 1-11, 13-15 and 17-18 now are presented for examination.

35 U.S.C. § 112 Rejection

Claims 8, 12, 14 and 16 stand rejected under 35 U.S.C. §112, second paragraph, as being indefinite for failing to particularly point out and distinctly claim the subject matter which applicant regards as the invention.

Claims 12 and 16 stand rejected under 35 U.S.C. §112, first paragraph, as failing to comply with the enablement requirement.

Claims 8 and 14 have been amended to obviate the Examiner's rejection.

Claims 12 and 16 have been cancelled without prejudice.

35 U.S.C. § 103 Rejection

Claims 1-5, 7, 11-12 and 15-17 are rejected under 35 U.S.C. §103(a) as being unpatentable over Hsieh U.S. Patent No. 6,564,986 ("Hsieh"), in view of Stewart et al., U.S. Application No. 2003/0170450 ("Stewart").

Hsieh discloses that the "BGA IC package is modified to link associated pairs of solder balls, e.g., *using wire bonding to form an upper portion of the daisy chain.*

Mounting the BGA IC package on the test PCB completes the daisy chain. By alternating between the test PCB contact pads that are linked by conductive traces and the *solder balls that are linked by wire bonding, the daisy chain provides a conductive path that*

passes through all solder balls of the BGA IC package.” (Abstract). Stewart discloses a “solid or semi-solid thermoplastic adhesive adhered to a surface mount electronic device . . . [and is] applied to any available surface on the connecting substrate of the surface mounted electronic device.” (Abstract).

In contrast, claim 1, in pertinent part, recites “applying a bonder to the parameters of the BGA package, wherein the bonder is applied independently of the array of solder balls, and the bonder is applied surrounding the array of solder balls.” (emphasis provided). The *daisy chain* of Hsieh is not the same as applying a bonder to the parameters of the BGA package such that the bonder is applied independently of the array of solder and surrounding the array of solder balls as recited by claim 1. As with Hsieh, Stewart also does not teach or reasonably suggest the applying the bonder to the parameter of the BGA package, as recited by claim 1, and as such, fails to disclose those limitations that are missing from Hsieh.

Claim 11, in pertinent part, further recites, applying bonder balls . . . independently of the array of solder and surrounding the array of solder balls. Neither Hsieh nor Stewart, independently or when combined, teach or reasonably suggest applying the bonder balls as recited by claim 11. Hence, Stewart adds nothing relevant to Hsieh at least with respect to claims 1 and 11. Accordingly, Applicants respectfully request the withdrawal of the rejections of claims 1 and 11 and their dependent claims.

Claims 6, 8-10, 14 and 18 are rejected under 35 U.S.C. §103(a) as being unpatentable over (“Hsieh”), in view of (“Stewart”) and in further view of Austin, et al., U.S. Patent No. 6,284,173 (“Austin”).

Claim 13 stands rejected under 35 U.S.C. §103(a) as being unpatentable over (“Hsieh”), in view of (“Stewart”) and in further view of Longgood, U.S. Patent No. 6,045,032 (“Longgood”).

Claims 6, 8-10, 13-14 and 18 depend from one of independent claims 1 or 11 and thus include the limitations of their base claim. Accordingly, Applicants respectfully request the withdrawal of the rejection of claims 6, 8-10, 13-14 and 18.

Conclusion

In light of the foregoing, reconsideration and allowance of the claims is hereby earnestly requested.

Invitation for a Telephone Interview

The Examiner is requested to call the undersigned at (303) 740-1980 if there remains any issue with allowance of the case.

Request for an Extension of Time

Applicants respectfully petition for an extension of time to respond to the outstanding Office Action pursuant to 37 C.F.R. § 1.136(a) should one be necessary. Please charge our Deposit Account No. 02-2666 to cover the necessary fee under 37 C.F.R. § 1.17(a) for such an extension.

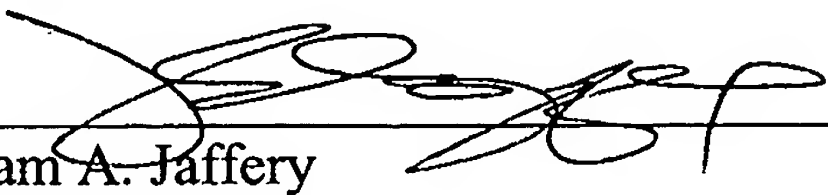
Charge our Deposit Account

Please charge any shortage to our Deposit Account No. 02-2666.

Respectfully submitted,

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